

AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph on page 1, line 18 as follows:

As semiconductor devices have become more highly integrated in recent years, circuit interconnections have become finer and devices to be integrated have been multilayer devices. Therefore, it is necessary to planarize a surface of a semiconductor wafer. It has been customary to remove surface irregularities from the surface of the semiconductor wafer by a chemical mechanical polishing (CMP) process ~~for thereby planarizing~~ so as to planarize the surface of the semiconductor wafer.

Please amend the title on page 4, line 32 as follows:

~~Disclosure~~ Summary of the Invention

Please amend the title on page 15, line 29 as follows:

~~Best Mode for Carrying Out~~ Detailed Description of the Invention